

Abstract

Method and apparatus for deflashing of integrated circuit packages.

5

This invention relates to a method and apparatus for deflashing integrated circuit (IC) packages by laser irradiation. The method and apparatus include two lasers scanning flash area for performing deflashing operation. CO₂ laser is used to remove top layer of flash and YAG laser is used to remove the thin layer of flash remained after CO₂ laser deflashing. CO₂ laser deflashing and following YAG laser deflashing can effectively remove flash and avoid damage of heat sinks as well as leads and bars in the IC packages.

10
Fig. 1